

The diagram illustrates a plasma processing system. At the top, a copper (Cu) antenna (3) is connected via a waveguide (2) to a matching network (21, 22) and a power source (Ps). The antenna is positioned above a substrate (6) which is mounted on a pedestal (7). The pedestal is surrounded by a magnetic field coil (Rm). A duct (Du) extends from the bottom of the pedestal. The entire assembly is housed within a chamber (1) equipped with various ports (11, 12, 13, 14) and a pressure gauge (12). The substrate (6) is supported by a complex support structure (4) consisting of multiple layers (41, 42, 43) and a central electrode (44). Gas inlets (41, 42, 43) are provided for process gases. A magnetic field coil (Rm) is used to generate a magnetic field around the pedestal. A pressure gauge (12) monitors the chamber pressure. A gas flow controller (13) manages the gas input. A power source (Ps) provides energy to the antenna through a matching network (21, 22).

FIG.2

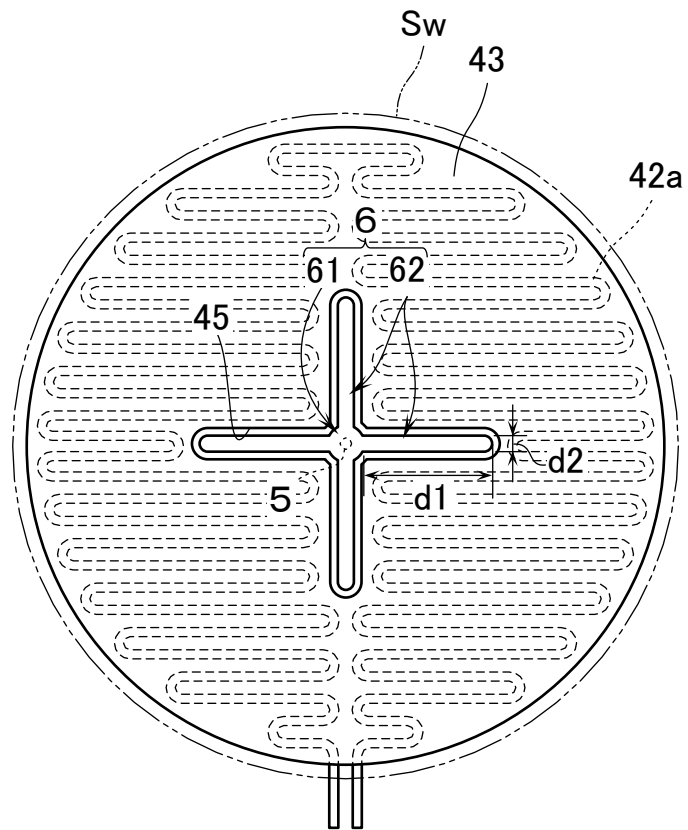


FIG.3

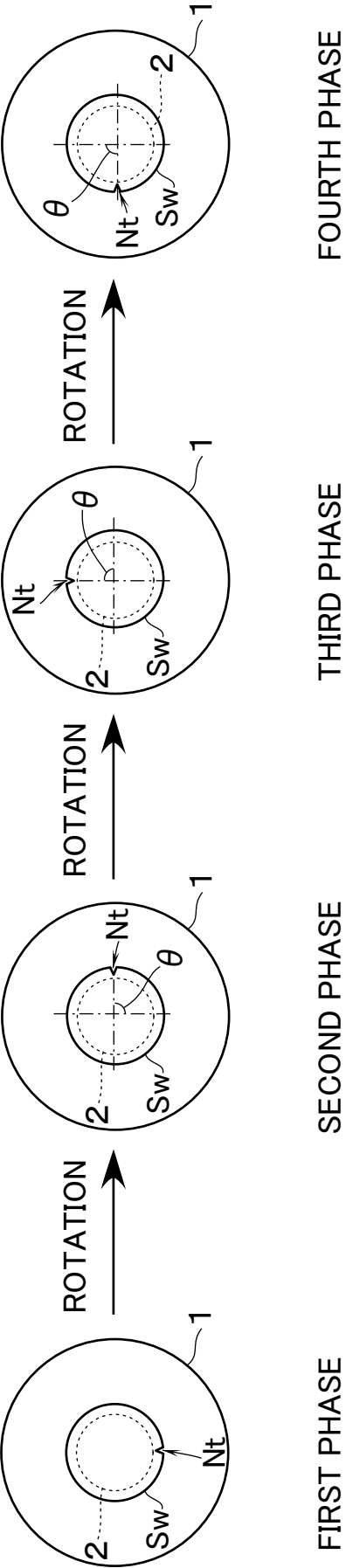


FIG.4

